

A DOMAIN-SPECIFIC TPU SUPERCOMPUTER FOR TRAINING DEEP NEURAL NETWORKS

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With contributions from Thomas Norrie, Nishant Patil, and many others

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Outline

- The Origin of TPUv2
- Requirements: Training vs. Inference
- Aiming Ahead of Our Moving Target
- Implementation Tradeoffs
- TPUv2
- TPUv3
- Systems and Performance
- References

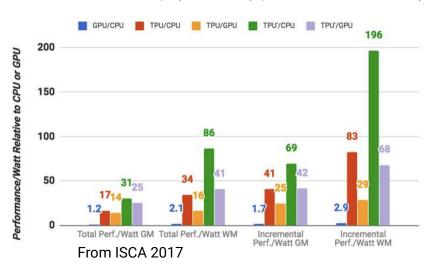
The Origin of TPUv2



Late 2013

- <u>TPUv1</u> project started
 - TPU = Tensor Processing Unit, an example of a DSA
 - DSA = Domain-specific architecture
 - Tensor = multidimensional array
- Provided >10X better perf/TCO than contemporary alternatives
 - perf/TCO = end-to-end performance / total cost of ownership (including power over lifetime)
 - Simple to deploy PCIe card
 - But it only accelerates inference



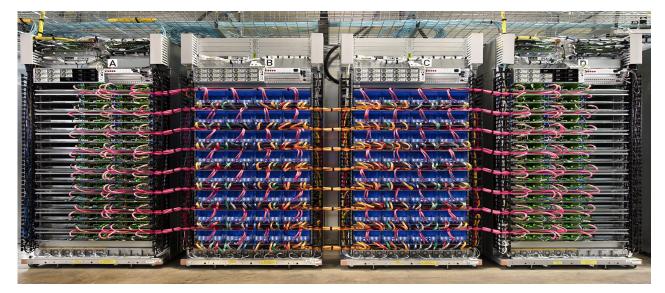


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- TPUv1 was being fabbed
- We realized training capability was the limiting factor to producing models
- People thought a DSA chip for ML training would be too complicated to build

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- TPUv1 was being fabbed
- We realized training capability was the limiting factor to producing models
- People thought a DSA chip for ML training would be too complicated to build
- So we decided to build a DSA chip plus an ML training supercomputer!



Basic Plan

Don't invent anything more than necessary

- Required to meet aggressive schedule
- TPU team only ~3X larger than CDC 6600 team

Thomas J. Watson Jr.'s 1963 IBM memo on the CDC6600:

Last week CDC had a press conference during which they officially announced their 6600 system. I understand that in the laboratory developing this system there are only 34 people, "including the janitor." Of these, 14 are engineers and 4 are programmers, and

Contrasting this modest effort with our own vast development activities. I fail to understand why we have lost our industry leadership position by letting someone else offer the world's most powerful computer.

- Aside: 6600 was a DSA for HPC vs. general-purpose 360 for all applications
- Codesign from compiler down to chip physical design
 - Early XLA team part of design team
- Start from a typical vector CPU architecture and add matrix operations
 - Similar to how the <u>Cray-1</u> extended previous scalar machines with vector operations
 - Advantage: start with an architecture type having compilers and add stuff
 - Leverage known compiler techniques for handling matrices in HPC (e.g., blocking, loop unrolling)
- Connect chips with very high bandwidth torus
 - Non-coherent distributed shared memory
 - Much higher bandwidths with lower costs than a datacenter network like ethernet or infiniband
 - Similar to the Cray T3E, but simpler

Cray-1 Architecture

Circa 1975



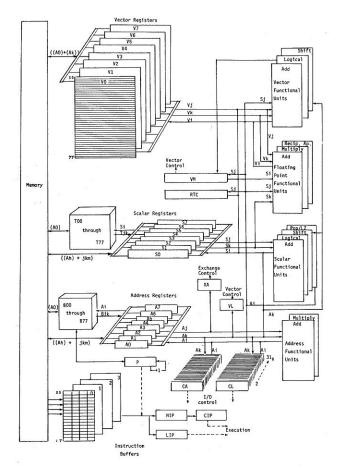


Figure 3-1. Computation section

This part looks like previous CDC6600 and CDC7600 machines

Cray-1 Architecture

<u>Circa 1975</u>



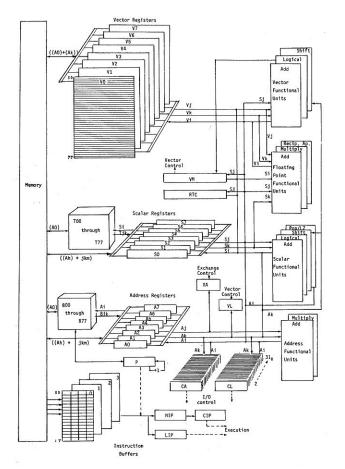


Figure 3-1. Computation section

Cray-1 added vector hardware in a consistent manner

This part looks like previous CDC6600 and CDC7600 machines

Aside: Tensor Processing and Computer History

- The universe is built with <u>tensor fields</u>
 - Einstein's <u>general theory of relativity</u> is expressed in tensor mathematics
- Computers have been working on tensor problems since Eniac
 - Original Eniac mission was <u>computing artillery tables</u> based on ballistics vs. temperature, wind speed, and direction
- Early computers tried to accelerate matrix operations with multiple scalar issue
 - o IBM ACS project involving up to 200 people from 1961-1969 without resulting in a product
- Cray accelerated them with vectors
 - The Cray architecture in the 1970's
- Only recently (thanks to Moore's Law) have we been able to build machines that can natively operate on >100x100 matrices in 1 cycle (albeit at lower precision)
 - o TPUs

Requirements: Training vs. Inference

Training and Inference Are Very Different Problems

	Training Inference		
Operations per solution	3.5 x 10 ²⁰ (MLP0)	1.2 x 10 ⁸ (MLP0)	
Solution latency	Hours or days	7-10 milliseconds	
Location	Key ML hubs	>20 locations worldwide	
Data size	Petabytes	Modest real-time user input	
Metrics	Perf/TCO and capability	Perf/TCO at latency goal	

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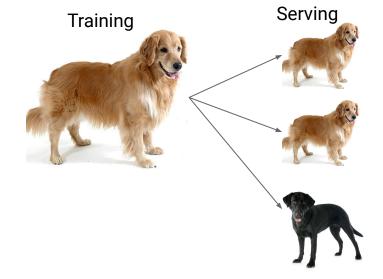
No. We'll show how to support both with the same DSA.

Overview of Inference Goals at Google

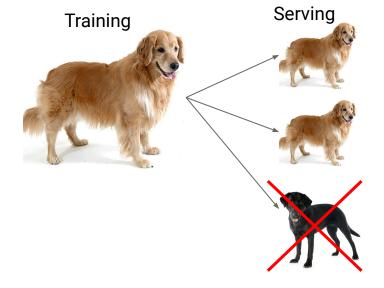
- Support high-velocity new model deployment
 - WYTIWYS (What You Train Is What You Serve)
 - Move from training to serving in minutes, not months
 - Leverage biggest investment: models and software
- Support many inference models on one device
 - Multitenancy (supported with HBM memory)
- Serve models with the required latency goal: SLO
 - SLO = Service Level Objective
 - Provide low TCO without sacrificing flexibility
 - BTW, lower latency than required wastes resources
- Enables rapid rollout of new product capabilities



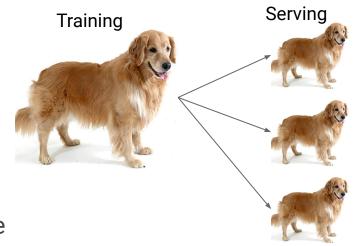
WYTIWYS?



WYTIWYS?



WYTIWYS



- WYTIWYS: What You Train Is What You Serve
 - Use same software stack for inference and training
 - Performance correlation if it trains well, inference on same core should work similarly
 - Provides same exception behavior if it trains well, inference shouldn't cause an exception
 - Avoids accuracy problems some customers have very stringent requirements
 - Subtle quantization problems delayed rolling out a TPUv1 model by months
- Luiz Barroso: "We want to train models overnight and deploy them the next day without the involvement of anyone with ML experience."
 - This is possible with WYTIWYS

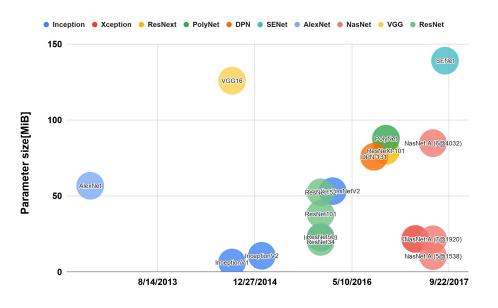
Multitenancy

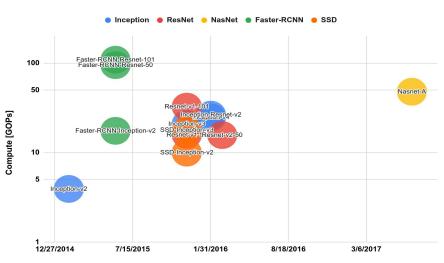
- Many inferencing applications need to support multiple models
 - Near zero switching time between models (e.g., <100 us)
- Examples:
 - Main model plus experimental models at various load percentages
 - Translate many different language pairs and models
 - Securely timeshare a TPU among multiple customers
- Poses challenges for SRAM-only inference architectures
 - Loading parameters from host when switching between models is slow
- HBM (High Bandwidth Memory) enables seamless switching



Aiming Ahead of Our Moving Target

Image Model Size Over Time



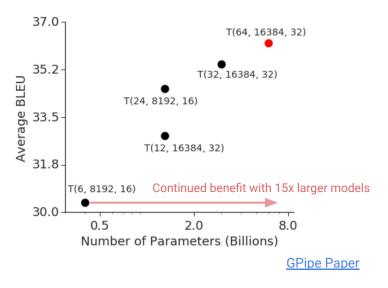


Parameter size of Imagenet models vs. time.

Compute Requirements of Imagenet models vs. time.

~10X model size growth in 4 years = 78% per year

Translate Model Size Trends

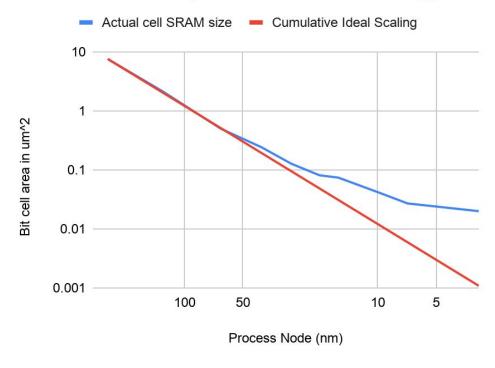


Recent research directions:

 <u>Gshard</u> multilingual neural machine translation transformer model with sparsely-gated mixture-of-experts with up to 600B parameters!

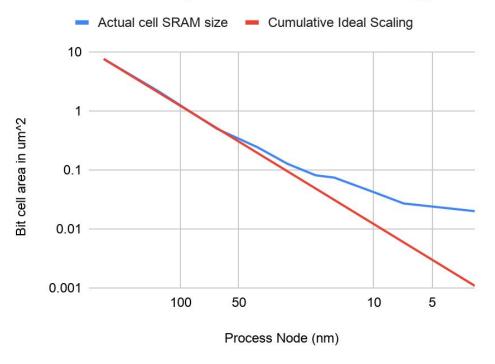
SRAM Scaling Trends

SRAM Scaling vs. Process Technology



SRAM Scaling Trends

SRAM Scaling vs. Process Technology



On-chip SRAM not scaling; >10X gap

1+ year design, 1+ year deployment, 3+ year service

- Scrimping on memory can be one of the easiest ways to reduce cost
- But memory requirements have grown incessantly since the first computers
 - EDSAC (1949) only had <u>1KB of memory</u>
 - Remember "640KB ought to be enough for anybody"?
- At current rates in next 5 years, model memory requirements could grow by:
 - \circ 1.75⁵ = 16X!
 - But on-chip SRAM isn't scaling!
- Need a memory hierarchy with DRAM
 - On-chip SRAM plus off-chip high-bandwidth memory
- Adequate memory provisioning raises costs in the near term
 - But increases the useful lifetime dramatically -> net positive

Implementation Tradeoffs



SRAM Accesses Consume a Lot of Power

• 2014 data from Mark Horowitz's Computing's Energy Problem:

Integer		FP	
Add		FAdd	
8 bit	0.03pJ	16 bit	0.4pJ
32 bit	0.1pJ	32 bit	0.9pJ
Mult		FMult	
8 bit	0.2pJ	16 bit	1.1pJ
32 bit	3.1pJ	32 bit	3.7pJ

(64bit)
10pJ
20pJ
100pJ
1.3-2.6nJ

SRAM Accesses Consume a Lot of Power

• 2014 data from Mark Horowitz's Computing's Energy Problem:

Integer		FP		Memory	
Add		FAdd		SRAM	(64bit)
8 bit	0.03pJ	16 bit	0.4pJ	8KB	10pJ
32 bit	0.1pJ	32 bit	0.9pJ	32KB	20pJ
Mult		FMult		1MB	100pJ
8 bit	0.2pJ	16 bit	1.1pJ	DRAM	1.3-2.6nJ
32 bit	3.1pJ	32 bit	3.7pJ		

Since 2014 computation has gotten ~3X cheaper but SRAM is still about the same

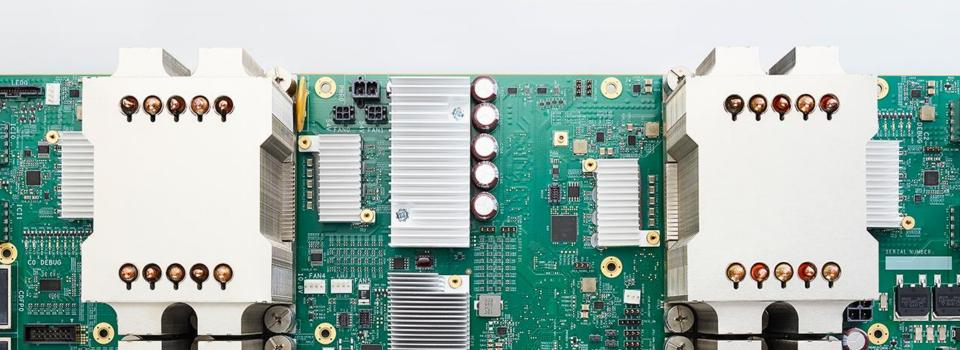
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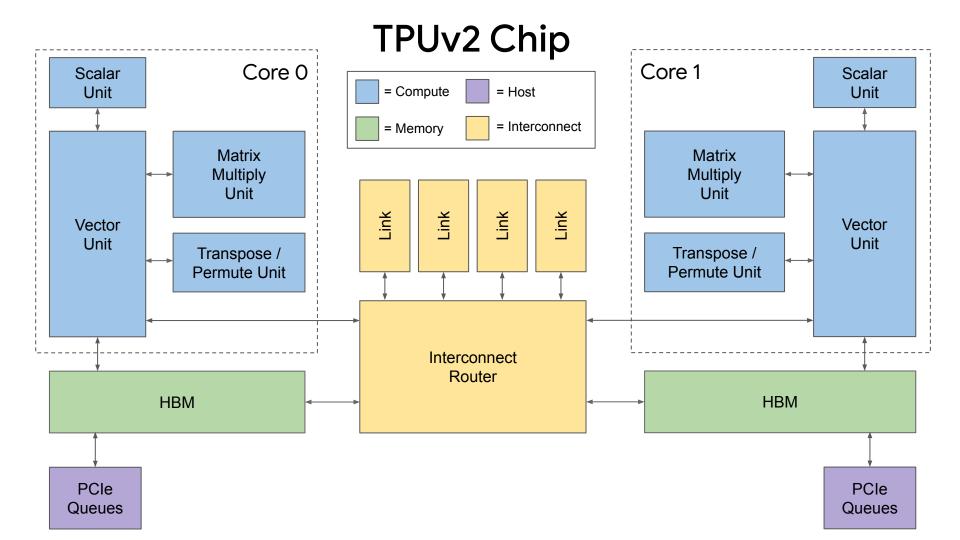
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Integer		FP		Memory	
Add		FAdd		SRAM	(64bit)
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32 bit	0.1pJ	32 bit	0.9pJ	32KB	20pJ
Mult		FMult		1MB	100pJ
8 bit	0.2pJ	16 bit	1.1pJ	DRAM	1.3-2.6nJ
32 bit	3.1pJ	32 bit	3.7pJ		

- Since 2014 computation has gotten ~3X cheaper but SRAM is still about the same
- Data reuse is REALLY important for efficiency (and FLOPs are cheap)

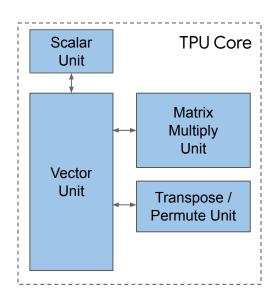
TPUv2





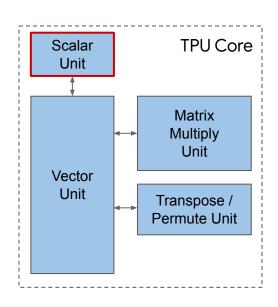
TPU Core

- VLIW Architecture
 - Leverage known compiler techniques
- Linear Algebra ISA
 - Scalar, vector, and matrix
 - Built for generality

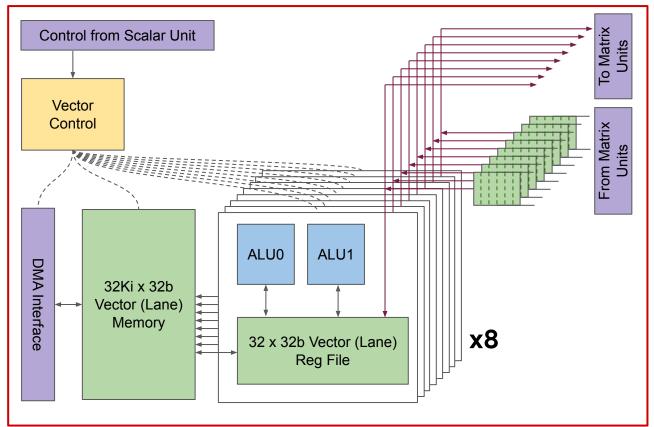


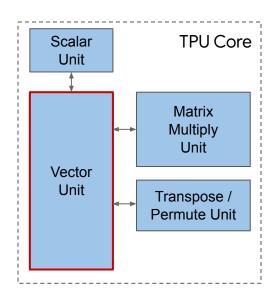
TPU Core: Scalar Unit

- 322b VLIW bundle
 - 2 scalar slots
 - 4 vector slots (2 for load/store)
 - 2 matrix slots (push, pop)
 - 1 misc slot
 - 6 immediates
- Scalar Unit performs:
 - Full VLIW bundle fetch and decode
 - Scalar slot execution



TPU Core: Vector Unit (Lane)

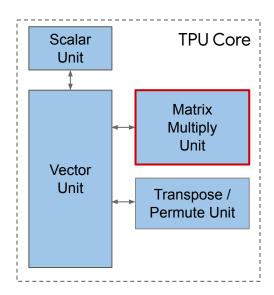


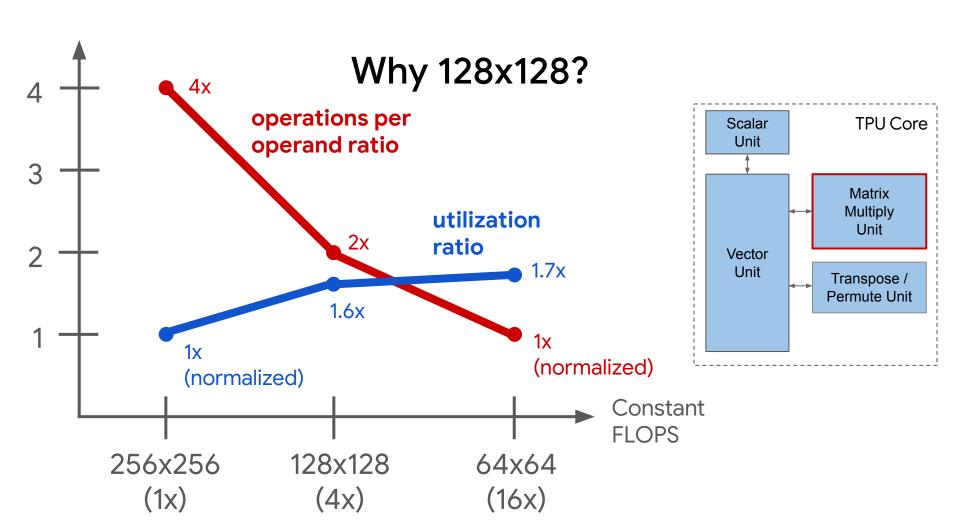


x128

TPU Core: Matrix Multiply Unit

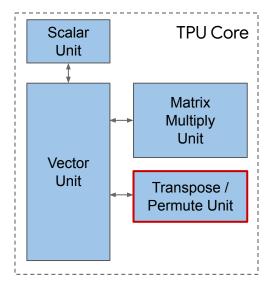
- 128 x 128 systolic array
 - Streaming LHS and results
 - Stationary RHS (w/ optional transpose)
- Numerics
 - bfloat16 multiply
 - \blacksquare {s, e, m} = {1, 8, 7}
 - float32 accumulation



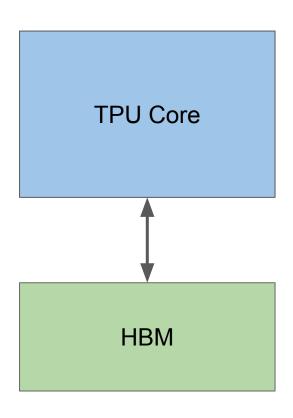


TPU Core: Transpose, Reduction, Permute Unit

- Efficient common matrix transforms
 - Transpose
 - Reduction
 - Permutation
- Reshuffle data across vector lanes



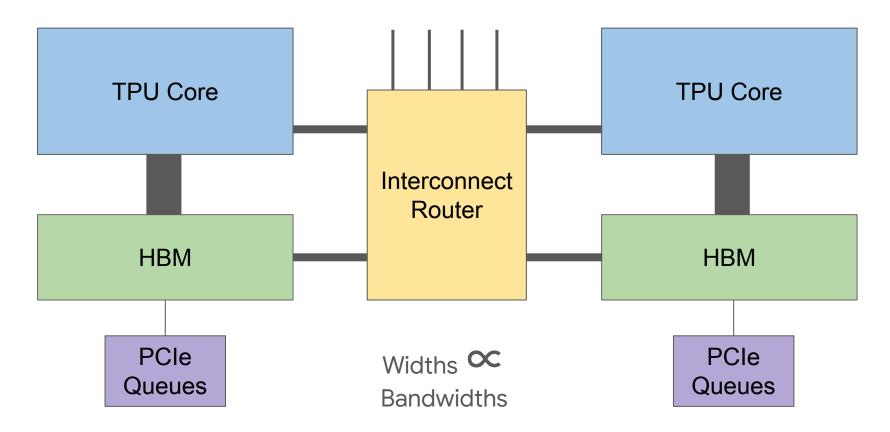
Memory System



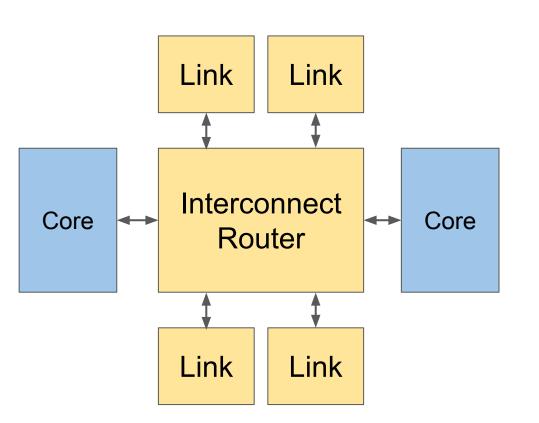
- Loads and stores against SRAM scratchpads
- Provides predictable scheduling within the core
- Can stall on sync flags

- Accessible through asynchronous DMAs
- Indicate completion in sync flags

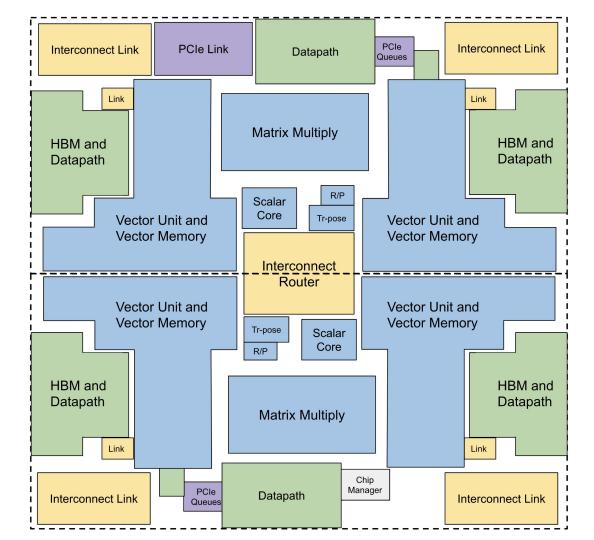
"Speeds and Feeds"



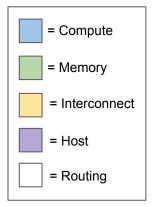
Non-coherent Shared Memory Interconnect



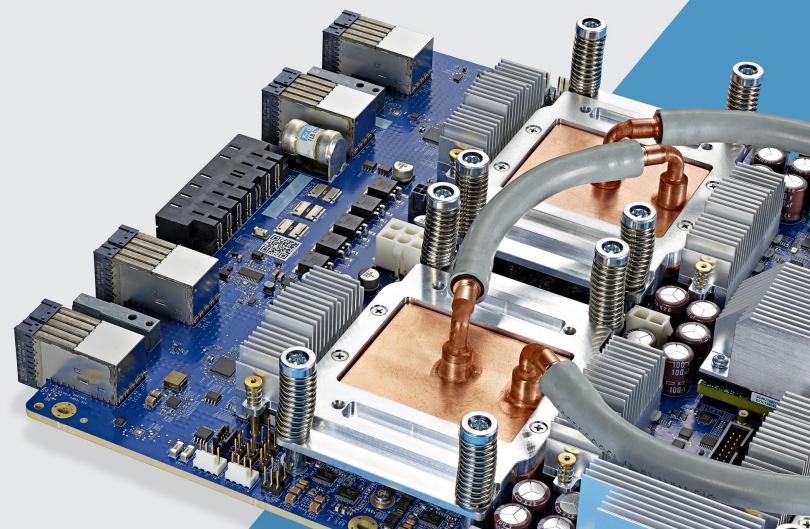
- On-die router with 4 links
- 500 Gbps per link
- Assembled into 2D torus
- Software view:
 - Uses DMAs just like HBM
 - Restricted to push DMAs
 - Simply target another chip id

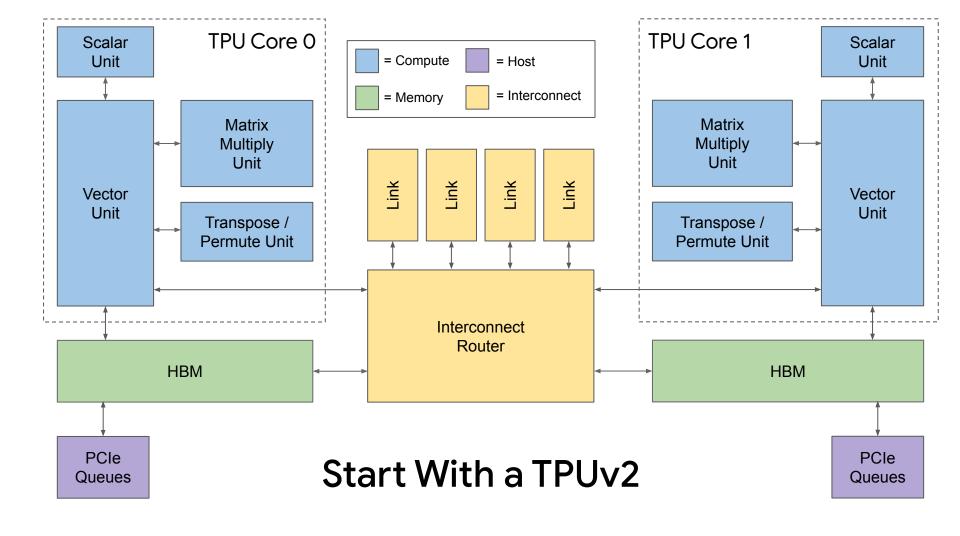


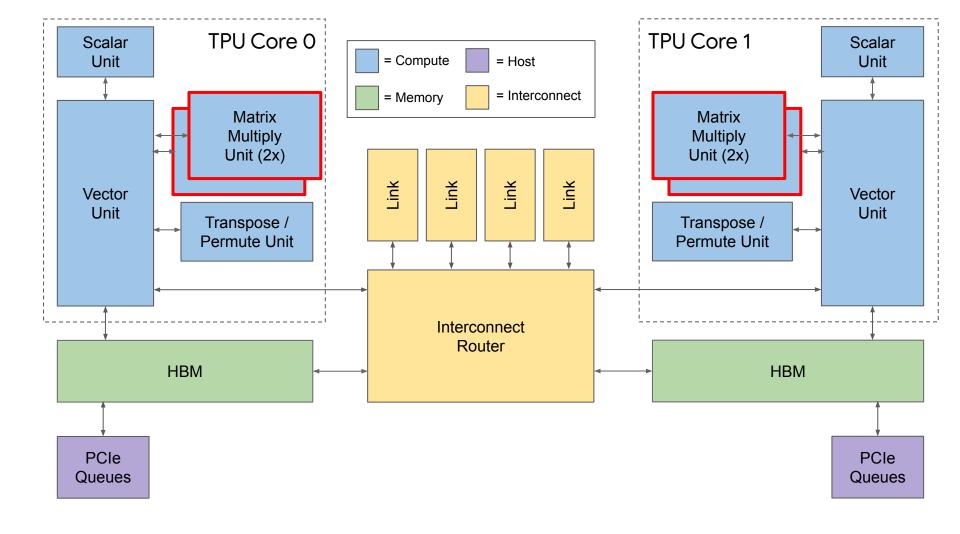
Floorplan

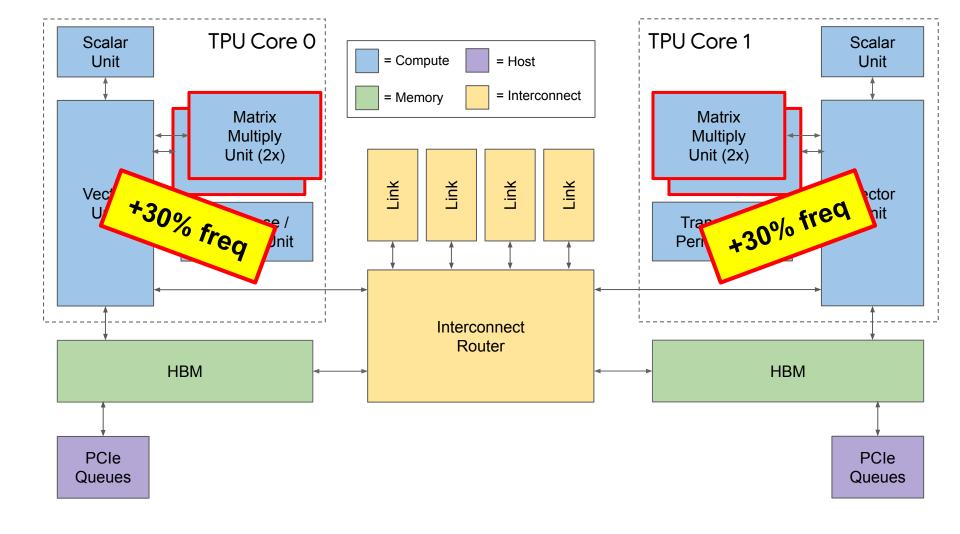


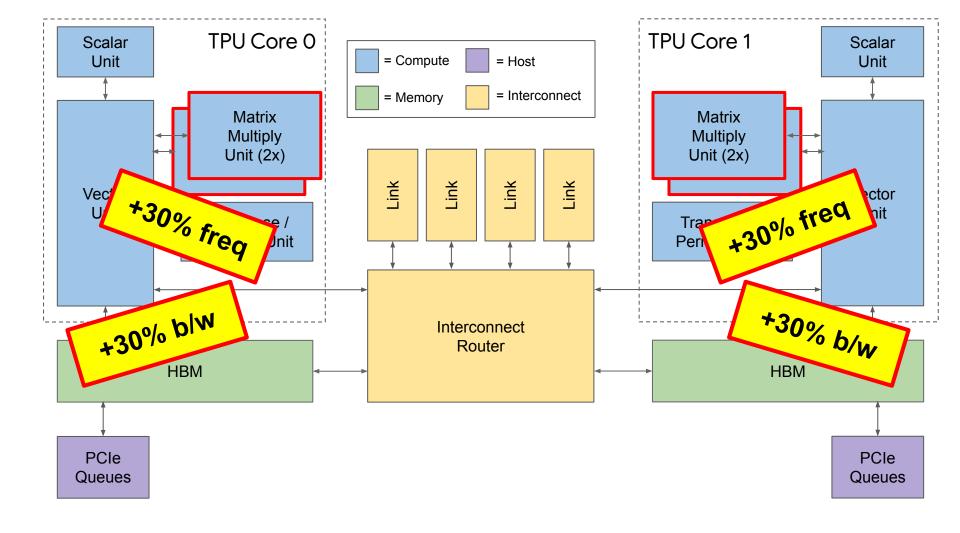
TPUv3

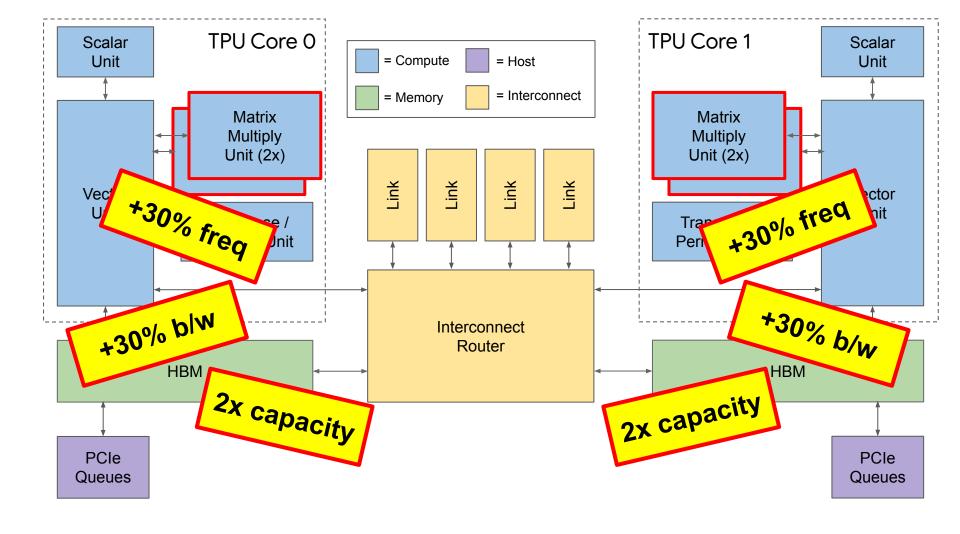


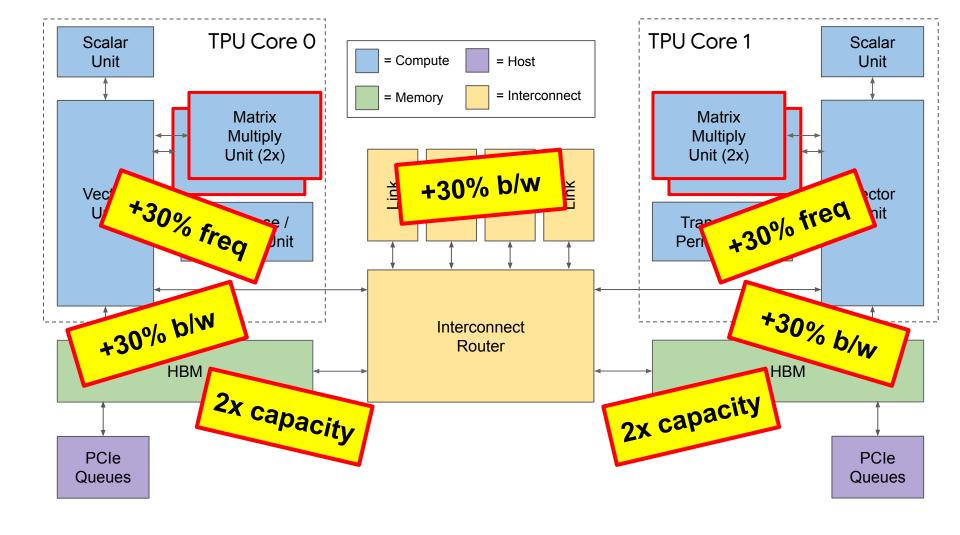


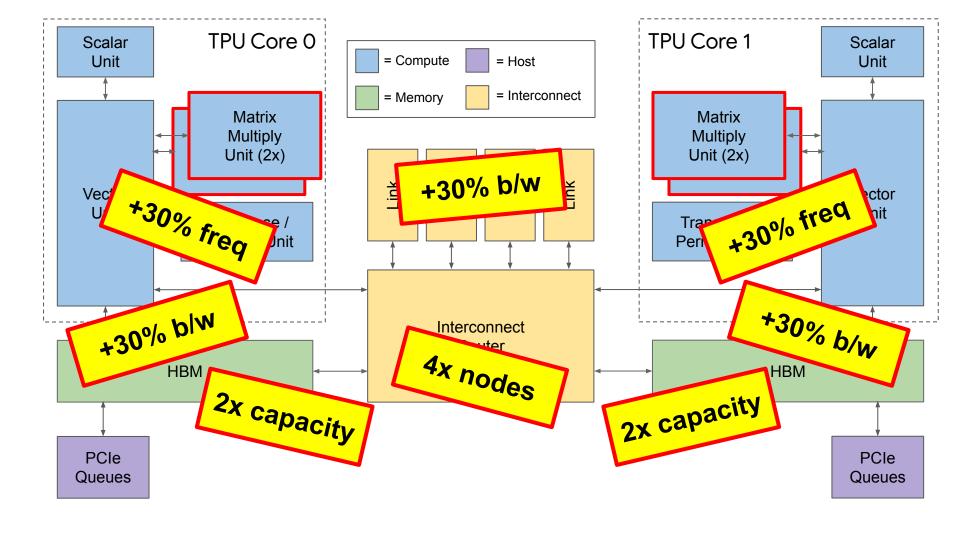


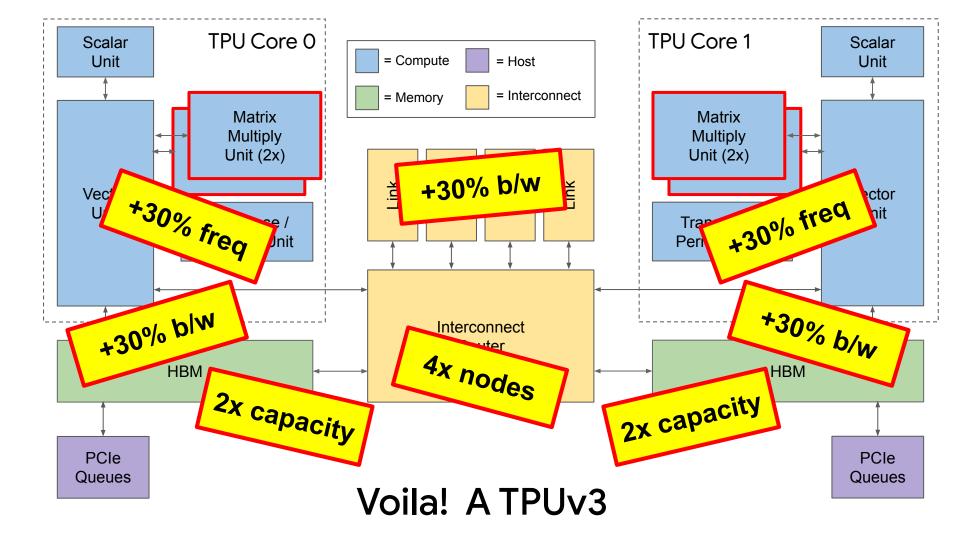


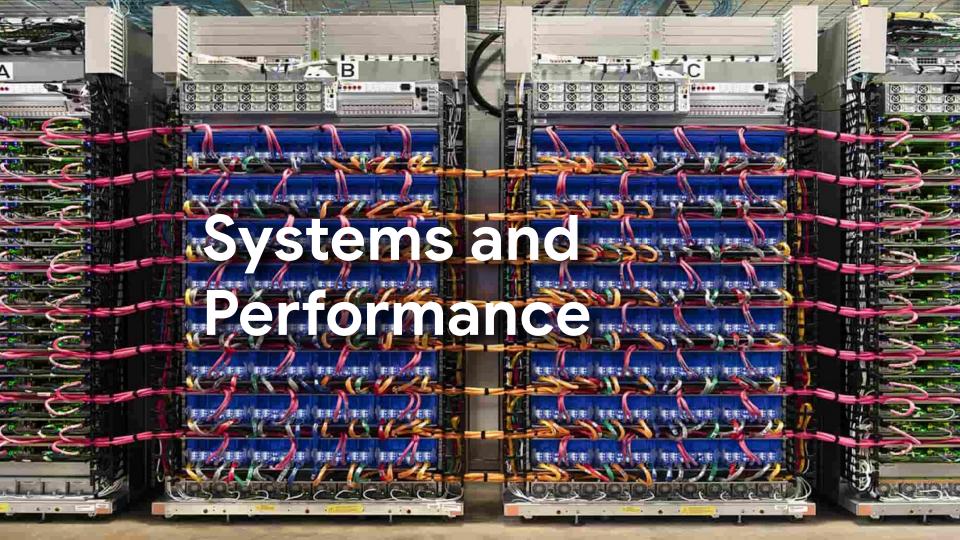








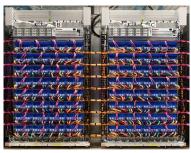




- TPUv1: single-chip system—built as coprocessor to a CPU
 - Works well for inference

- TPUv2 & TPUv3: ML supercomputers
 - Multi-chip scaling critical for practical training times
 - Single TPUv2 chip would take 60 400 days for production workloads

TPUv2 supercomputer (256 chips)



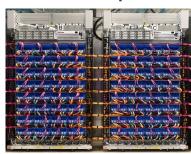
TPUv2 boards = 4 chips

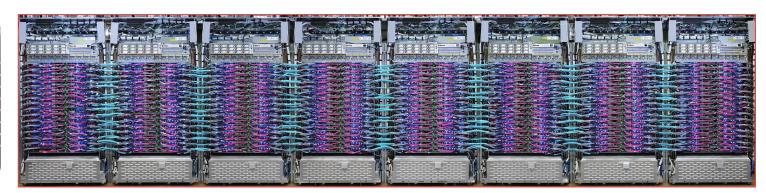


TPUv2 supercomputer

TPUv3 supercomputer (1024 chips)

(256 chips)

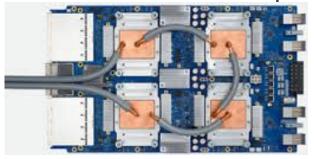




TPUv2 boards = 4 chips

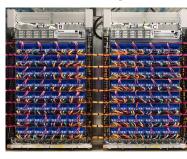


TPUv3 boards = 4 chips



TPUv2 supercomputer

(256 chips)





11.5 petaflops

4 TB HBM

2-D torus

256 chips

> 100 petaflops

32 TB HBM

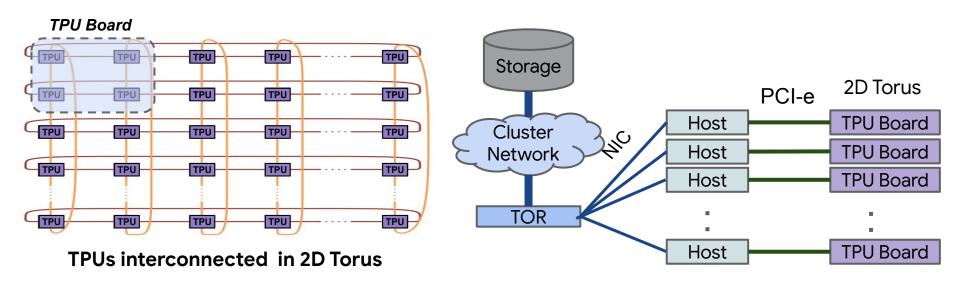
TPUv3 supercomputer (1024 chips)

Liquid cooled

New chip + larger-scale system

1024 chips

TPU Training Pod Architecture



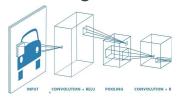
Shared-memory interconnect for **synchronous** parallel training

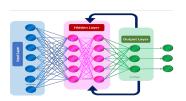
6 Production Applications

- MultiLayer Perceptrons (MLP)
 - MLPO is unpublished
 - MLP1 is RankBrain [Cla15]

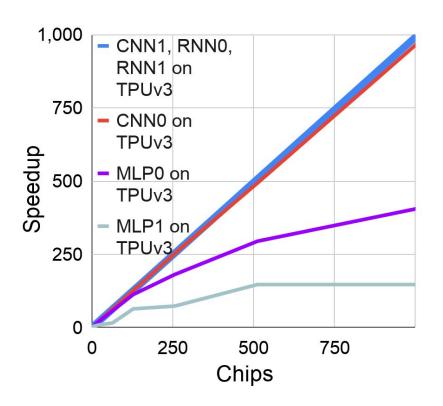
Input layer Hidden layers Output layer

- Convolutional Neural Networks (CNN)
 - CNNO is AlphaZero, which mastered the games chess, Go, and shogi [Sil18]
 - CNN1 is an Google-internal model for image recognition
- Recurrent Neural Networks (RNN)
 - RNNO is a Translation model [Che18]
 - RNN1 is a Speech model [Chi18]





TPUv3 Supercomputer Scaling: 6 Production Apps



MLPO & MLP1

- 40% & 14% of perfect linear scaling
- Limited by embeddings

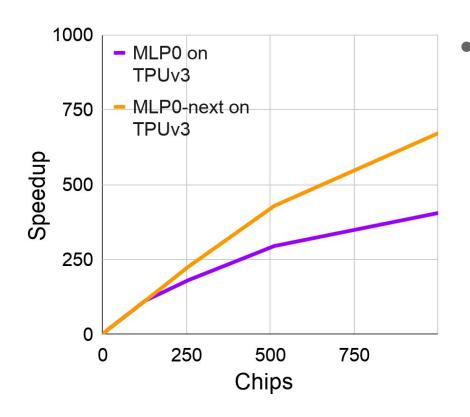
CNNO

96% of perfect linear scaling!

CNN1, RNNO, RNN1

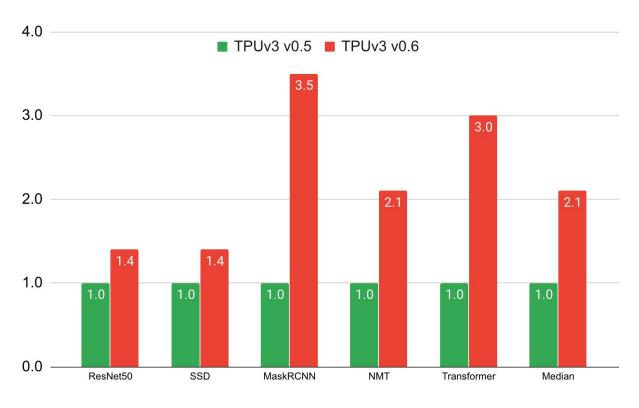
3 production apps run at 99% of perfect linear scaling at 1024 chips!

TPUv3 Supercomputer Scaling: MLPO-next vs. MLPO



- Improved scaling for newer larger models and SW improvements for better quality
 - MLP0-next: 67% of perfect linear
 scale at 1024 chips
 - Up from 40% from MLP0

Software Speedup: MLPerf v0.5 vs. v0.6



Compiler and software stack advances also sped up production apps:

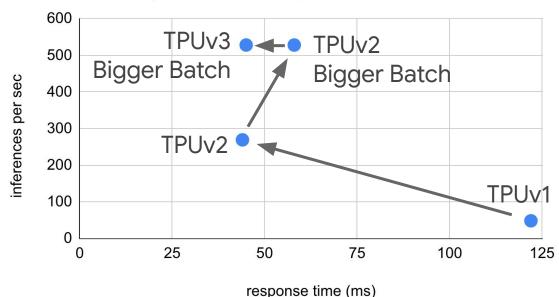
- CNNO 1.8x (more bfloat16 use)
- MLPO 1.6x (better partitioning and placement of embeddings)

Compiler and software stack optimizations enable larger models for improved accuracy

Inference: TPUv2/v3 vs TPUv1

- Inference similar to forward pass of training
- Bfloat16 numerics provide WYTIWYS in TPUv2/v3 vs int8 in TPUv1

LSTM0 Inferences per second and response time



Key Takeaways

- Current chip technologies enable support of matrices as a fundamental data type
- When designing a new architecture it is important to learn from the lessons of past HW and SW
- Using the same HW and SW for both training and inference (WYTIWYS) supports reliable, accurate, and high-velocity model deployment



Used across many products

























References

- "A Domain-Specific Supercomputer for Training Deep Neural Networks" Norman P. Jouppi, Doe Hyun Yoon, George Kurian, Sheng Li, Nishant Patil, James Laudon, Cliff Young, David Patterson, Communications of the ACM, July 2020, Vol. 63 No. 7, Pages 67-78.
- "Google's Training Chips Revealed: TPUv2 and TPUv3", Thomas Norrie, Nishant Patil, Doe Hyun Yoon, George Kurian, Sheng Li, James Laudon, Cliff Young, Norman P. Jouppi, and David Patterson, IEEE Hot Chips Symposium, August, 2020.

Q&A

